

N-Channel MOSFET

General Description

The WSK40200 use advanced SGT MOSFET technology to provide low $R_{DS(ON)}$, low gate charge, fast switching, and excellent avalanche characteristics.

This device is specially designed to get better ruggedness and suitable to use in Synchronousrectification applications.

Features

- Low R_{DS(ON)} & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Fast switching and soft recovery
- Invertors
- Synchronous-rectification applications

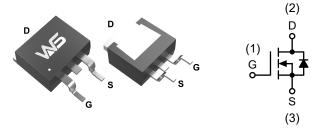
Product Summery

BV _{DSS}	R _{DS(ON)}	Ι _D
40V	1.5mΩ	200A

Applications

- Consumer electronic power supply
- Motor control
- Synchronous rectification
- Isolated DC
- Synchronous-rectification applications

TO-263-2L Pin Configuration



Absolute Maximum Ratings (T_J=25°C, Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	40	V
V _{GS}	Gate-Source Voltage	±20	V
Ι _D	Continuous Drain Current ¹	200	٨
I _{DP}	Pulsed Drain Current ²	390	A
E _{AS}	Single Pulse Avalanche Energy ⁴	300	mJ
P _D	Power Dissipation ³	140	W
T _{STG}	Storage Temperature Range -55 to 150		°C
TJ	Operating Junction Temperature Range -55 to 150		

Thermal Data

Symbol	Parameter	Rating	Units
R _{θJA}	Thermal Resistance Junction-Ambient ⁵	62	°C/W
R _{θJC}	Thermal Resistance Junction-Case 0.89		C/W



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Electrical Characteristics (T_J=25°C, Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250µA	40			V
D	Statia Drain Source On Registeres	V _{GS} =10V , I _D =55A		1.5	2.0	
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V , I _D =55A 2.5		3.0	- mΩ	
V _{GS(th)}	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_{D}=250\mu A$	1.3	1.7	2.5	V
I _{DSS}	Drain-Source Leakage Current	V_{DS} =40V , V_{GS} =0V			1.0	μA
I _{GSS}	Gate-Body Leakage Current	V_{GS} =±20V, V_{DS} =0V			±100	nA
Qg	Total Gate Charge			96.8		
Q _{gs}	Gate-Source Charge	V_{DS} =20V , V_{GS} =10V , I_{D} =20A		14.5		nC
Q _{gd}	Gate-Drain Charge			18.4		
T _{d(on)}	Turn-on Delay Time			26.6		
Tr	Rise Time	V _{DS} =20V , V _{GS} =10V ,		9.3		
T _{d(off)}	Turn-off Delay Time	R _G =2Ω , I _D =20A		96		ns
T _f	Fall Time			39.3		
C _{iss}	Input Capacitance			6587		
C _{oss}	Output Capacitance	V _{DS} =20V , V _{GS} =0V , <i>f</i> =100KHz		2537		pF
C _{rss}	Reverse Transfer Capacitance			178		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
۱ _S	Continuous Source Current	V =V =0V Force Current			130	Δ
I _{SP}	Pulsed Source Current	V _G =V _D =0V, Force Current			390	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =20A			1.3	V
t _{rr}	Reverse Recovery Time	L = 20.4 di/dt= 10.04/up		205		ns
Q _{rr}	Reverse Recovery Charge	I _S =20A , di/dt=100A/µs		557.4		nC

Note:

- 1. Calculated continuous current based on maximum allowable junction temperature.
- 2. Repetitive rating: pulse width limited by max. junction temperature.
- 3. P_{D} is based on max. junction temperature, using junction-case thermal resistance.
- 4. V_{DD}=30V, R_G=6\Omega, L=0.3mH, starting T_J=25°C.
- 5. The value of R_{BJA} is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.



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Typical Characteristics

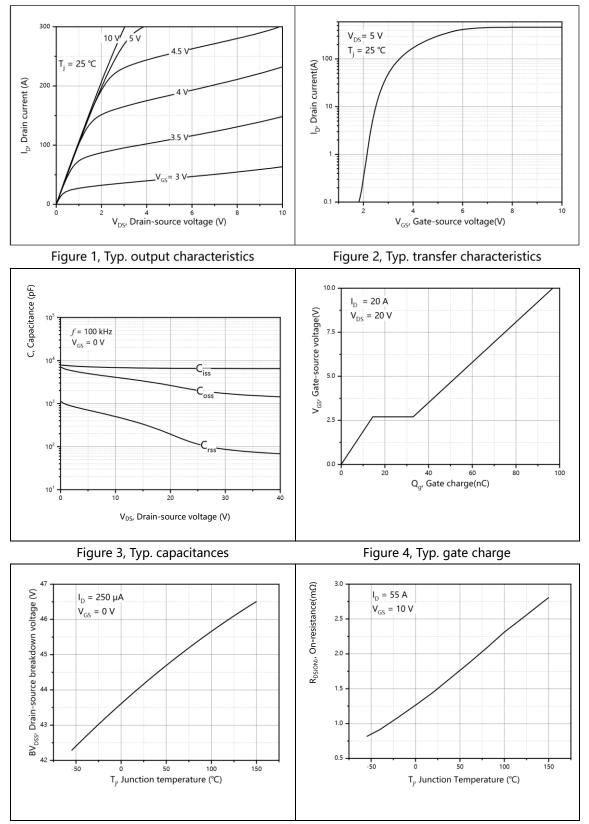


Figure 6, Drain-source on-state resistance



N-Channel MOSFET

Typical Characteristics (Cont.)

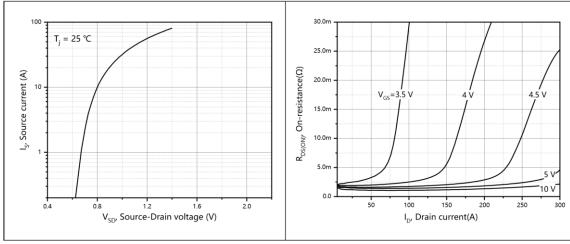


Figure 7, Forward characteristic of body diode

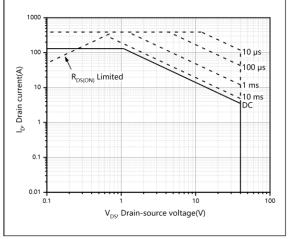


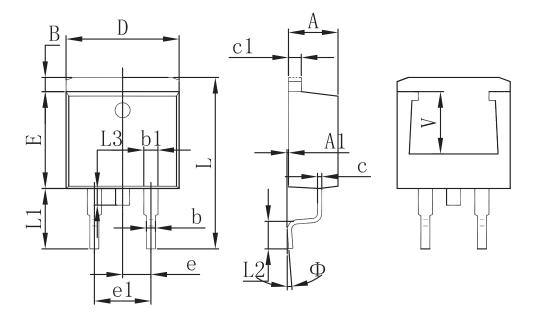
Figure 9, Safe operation area $T_C{=}25\ ^\circ C$

Figure 8, Drain-source on-state resistance



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Packaging information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	4.470	4.670	0.176	0.184	
A1	0.000	0.150	0.000	0.006	
В	1.120	1.420	0.044	0.056	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.310	0.530	0.012	0.021	
c1	1.170	1.370	0.046	0.054	
D	10.010	10.310	0.394	0.406	
E	8.500	8.900	0.335	0.350	
е	2.540	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204	
L	14.940	15.500	0.588	0.610	
L1	4.950	5.450	0.195	0.215	
L2	2.340	2.740	0.092	0.108	
L3	1.300	1.700	0.051	0.067	
Φ	0°	8°	0°	8°	
V	5.600 REF.		0.220REF.		



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